PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

Assignment ID: PATI204513

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Sujeet AYYAPUREDDI	09/08/2022
Yang LI	08/24/2022
Edmund GIESKE	08/29/2022
Cagda DIRIK	07/15/2022
Ameen D. AKEL	10/13/2023
Elliott C, COOPER-BALIS	07/18/2022
Amitava MAJUMDAR	08/24/2022
Danilo CARACCIO	01/12/2024
Robert M. WALKER	08/25/2022

RECEIVING PARTY DATA

Company Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 S. Federal Way
City:	Boise
State/Country:	IDAHO
Postal Code:	83716

PROPERTY NUMBERS Total: 2

Property Type	Number
Application Number:	17897813
Application Number:	63302050

CORRESPONDENCE DATA

Fax Number: 2409127587

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2409127587
Email: docketing@woodiplaw.com,tthomas@woodiplaw.com
Correspondent Name: Theodore A. Wood
Address Line 1: 555 Quince Orchard Road
Address Line 2: Suite 280
Address Line 4: Gaithersburg, MARYLAND 20878

ATTORNEY DOCKET NUMBER:	MICR/38002US

NAME OF SUBMITTER:	Tammi Thomas
SIGNATURE:	Tammi Thomas
DATE SIGNED:	05/03/2024

Total Attachments: 11

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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Sujeet **AYYAPUREDDI** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States	**2)**	Yang **LU** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States
3)	Edmund **GIESKE** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States	**4)**	Cagda **DIRIK** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States
5)	Ameen D. **AKEL** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States	**6)**	Elliot C. **COOPER-BALIS** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States
7)	Amitava **MAJUMDAR** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States	**8)**	Danilo **CARACCIO** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States
9)	Robert M. **WALKER** c/o Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 United States		

(hereinafter referred to as Assignors), have invented a certain invention entitled:

AREA-OPTIMIZED ROW HAMMER MITIGATION

☒ for which application for Letters Patent in the United States was filed on **January 22, 2022**, under Serial No**. 63/302,050.**

☒ I/we hereby authorize and request our attorneys, Wood IP, LLC of 555 Quince Orchard Road, Suite 280, Gaitherburg, MD, 20878, to insert here in parentheses (Application number **17/897,813** and filed **November 30, 2022**) the filing date and application number of said application when known;

and

WHEREAS, Micron Technology, Inc. ("Micron") a Delaware corporation, having a place of business at 8000 S. Federal Way, Boise, Idaho 83716 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

INVENTOR 1

Signature: Sujeet Date: 9/8/22
Sujeet **AYYAPUREDDI**

INVENTOR 2

Signature: ______________________ Date: ______________
Yang **LU**

INVENTOR 3

Signature: ______________________ Date: ______________
Edmund **GIESKE**

INVENTOR 4

Signature: ______________________ Date: ______________
Cagda **DIRIK**

INVENTOR 5

Signature: ______________________ Date: ______________
Ameen D. **AKEL**

INVENTOR 6

Signature: ______________________ Date: ______________
Elliot C. **COOPER-BALIS**

INVENTOR 1

Signature: ____________________ Date: ______________
Sujeet **AYYAPUREDDI**

INVENTOR 2

Signature: ____________________ Date: 08/24/2022
Yang **LU**

INVENTOR 3

Signature: ____________________ Date: ______________
Edmund **GIESKE**

INVENTOR 4

Signature: ____________________ Date: ______________
Cagda **DIRIK**

INVENTOR 5

Signature: ____________________ Date: ______________
Ameen D. **AKEL**

INVENTOR 6

Signature: ____________________ Date: ______________
Elliot C. **COOPER-BALIS**

INVENTOR 1

Signature: ______________________________ Date: ____________________
Sujeet **AYYAPUREDDI**

INVENTOR 2

Signature: ______________________________ Date: ____________________
Yang **LU**

INVENTOR 3

Signature: Edmund J. Gieske Date: August 29, 2022
Edmund **GIESKE**

INVENTOR 4

Signature: ______________________________ Date: ____________________
Cagda **DIRIK**

INVENTOR 5

Signature: ______________________________ Date: ____________________
Ameen D. **AKEL**

INVENTOR 6

Signature: ______________________________ Date: ____________________
Elliot C. **COOPER-BALIS**

INVENTOR 1

Signature: ____________________ Date: ____________

Sujeet **AYYAPUREDDI**

INVENTOR 2

Signature: ____________________ Date: ____________

Yang **LU**

INVENTOR 3

Signature: ____________________ Date: ____________

Edmund **GIESKE**

INVENTOR 4

Signature: ____________________ Date: 07/15/2022

Cagdas **DIRIK**

INVENTOR 5

Signature: ____________________ Date: ____________

Ameen D. **AKEL**

INVENTOR 6

Signature: ____________________ Date: ____________

Elliot C. **COOPER-BALIS**

INVENTOR 1

Signature: ____________________ Date: ______________
Sujeet **AYYAPUREDDI**

INVENTOR 2

Signature: ____________________ Date: ______________
Yang **LU**

INVENTOR 3

Signature: ____________________ Date: ______________
Edmund **GIESKE**

INVENTOR 4

Signature: ____________________ Date: ______________
Cagdas **DIRIK**

INVENTOR 5

Signature: Ameen Akel Date: 10/13/2023
Ameen D. **AKEL**

INVENTOR 6

Signature: ____________________ Date: ______________
Elliott C. **COOPER-BALIS**

INVENTOR 1

Signature: ______________________________ Date: ____________________
Sujeet **AYYAPUREDDI**

INVENTOR 2

Signature: ______________________________ Date: ____________________
Yang **LU**

INVENTOR 3

Signature: ______________________________ Date: ____________________
Edmund **GIESKE**

INVENTOR 4

Signature: ______________________________ Date: ____________________
Cagdas **DIRIK**

INVENTOR 5

Signature: ______________________________ Date: ____________________
Ameen D. **AKEL**

INVENTOR 6

Signature: ______________________________ Date: 7/18/22
Elliott C. **COOPER-BALIS**

[redacted]

INVENTOR 7

Signature: Amitava Majumdar
Amitava **MAJUMDAR**

Date: 08/24/2022

INVENTOR 8

Signature: ____________________________
Danilo **CARACCIO**

Date: ____________________

INVENTOR 9

Signature: ____________________________
Robert M. **WALKER**

Date: ____________________

INVENTOR 7

Signature: ______________________________ Date: ____________________
Amitava **MAJUMDAR**

INVENTOR 8

Signature: /Danilo Caraccio/ Date: 01/12/2024
Danilo **CARACCIO**

INVENTOR 9

Signature: ______________________________ Date: ____________________
Robert M. **WALKER**

INVENTOR 7

Signature: ____________________________ Date: ____________________
Amitava **MAJUMDAR**

INVENTOR 8

Signature: ____________________________ Date: ____________________
Danilo **CARACCIO**

INVENTOR 9

Signature: ____________________________ Date: 8-25-2022
Robert M. **WALKER**